

Listing of Claims

1. (Currently amended) An apparatus for applying semiconductor chips  $[(5)]$  to a plurality of substrates  $[(4)]$ , in particular smartcard modules or flexboards, wherein at an adhesive application device  $[(1)]$  adhesive is applied to the substrate  $[(4)]$  at predefined substrate positions, at a fitting device  $[(2)]$  the substrate  $[(4)]$  is fitted with the semiconductor chips  $[(5)]$  at the substrate positions, and in a curing device ~~(3, 3a, 3b, 3c, 3d)~~ the adhesive is cured, characterized in that the curing device ~~(3, 3a, 3b, 3c, 3d)~~ and/or a further device can be connected by a clamping device ~~(13, 14)~~ to a conveyor belt  $[(6)]$  which transports the substrates  $[(4)]$  along the devices, and can be moved in the transport direction, at a transport speed of the conveyor belt  $[(6)]$ , by a lifting device  $[(15)]$ .
  
2. (Currently amended) The apparatus as claimed in claim 1, characterized in that, in the curing device ~~(3, 3a, 3b, 3c, 3d)~~ and/or the further device which can be connected to the conveyor belt  $[(6)]$ , a plurality of processing and/or control units  $[(19)]$  are arranged in the transport direction of the conveyor belt  $[(6)]$ , which processing and/or control units carry out simultaneous processing and/or control of the substrates  $[(4)]$  fitted with the semiconductor chips  $[(5)]$  as they are transported.

3. (Currently amended) The apparatus as claimed in claim 2, characterized by a timer device for setting a time duration which corresponds to the sum of a processing and/or control time of a processing and/or control unit  $[(19)]$  and a time period which is required to return the moved curing device (~~3, 3a, 3b, 3c, 3d~~) and/or the further device to a starting position in a direction counter to the transport direction.
4. (Currently amended) The apparatus as claimed in claim 3, characterized in that arranged in the curing device (~~3, 3a, 3b, 3c, 3d~~) and/or the further device are the same number of processing and/or control units  $[(19)]$  as the number of substrates  $[(4)]$  moving in the transport direction which can be fitted by the fitting device  $[(2)]$  at a predefined fitting speed within the processing and/or control time.
5. (Currently amended) The apparatus as claimed in claim 1 ~~any of the preceding claims~~, characterized in that the movable curing device (~~3, 3a, 3b, 3c, 3d~~) comprises a thermode array  $[(18)]$  arranged above the conveyor belt  $[(6)]$ , said thermode array comprising a plurality of thermodes assigned to the substrate positions of the substrates  $[(4)]$ , and at least one heating plate  $[(1)]$  arranged below the conveyor belt  $[(6)]$ .

6. (Currently amended) The apparatus as claimed in claim 5, characterized in that the thermode array  $[(18)]$  and the heating plate  $[(21)]$  can be moved by a slide device in a direction perpendicular to the plane of the conveyor belt in such a way that, with the clamping device ~~(13, 14)~~ closed, they can be moved toward the conveyor belt  $[(6)]$  and away from the conveyor belt  $[(6)]$ .
7. (Currently amended) The apparatus as claimed in claim 1 ~~any of the preceding claims~~, characterized in that the clamping device comprises at least two clamping jaw units ~~(13, 14)~~ which are preferably arranged at end regions of the movable curing device ~~(3, 3a, 3b, 3c, 3d)~~ and/or of the further device the upper and lower clamping jaws ~~(24a, 25a; 24b, 25b)~~ of which can be guided toward the conveyor belt  $[(6)]$  from above and below.
8. (Currently amended) The apparatus as claimed in claim 1 ~~any of the preceding claims~~, characterized in that the lifting device  $[(5)]$  is connected to a conveyor belt drive for moving the conveyor belt in a step-wise manner in the transport direction.

9. (Currently amended) The apparatus as claimed in claim 3 ~~any of claims 3 to 8~~, characterized by a further clamping device ~~[[23]]~~, fixed to the apparatus, for keeping the conveyor belt ~~[[6]]~~ stationary while the moved curing device ~~(3, 3a, 3b, 3c, 3d)~~ and/or the further device is being returned in the direction counter to the transport direction.
10. (Currently amended) A method for applying semiconductor chips ~~[[5]]~~ to a plurality of substrates ~~[[4]]~~, in particular smartcard modules or flexboards, wherein at an adhesive application device ~~[[1]]~~ adhesive is applied to the substrate (4) at predefined substrate positions, at a fitting device ~~[[2]]~~ the substrate (4) is fitted with the semiconductor chips ~~[[5]]~~ at the substrate positions, and in a curing device ~~(3, 3a, 3b, 3c, 3d)~~ the adhesive is cured, characterized by the following steps:
- connecting the curing device ~~(3, 3a, 3b, 3c, 3d)~~ and/or a further device to a conveyor belt ~~[[6]]~~ which transports the substrates ~~[[4]]~~ along the devices, by closing a first clamping device ~~(13, 14)~~;
  - opening a second clamping device ~~[[23]]~~, fixed to the apparatus, so as to release the conveyor belt ~~[[6]]~~ moving in the transport direction;
  - moving processing and/or control units ~~[[19]]~~ arranged in the curing device ~~(3, 3a, 3b, 3c, 3d)~~ and/or the further device into a closed position in a direction perpendicular to the plane of the

conveyor belt;

- moving the curing device (~~3, 3a, 3b, 3c, 3d~~) and/or the further device at a transport speed of the conveyor belt  $[(6)]$  in the transport direction during a simultaneous processing and/or control of a plurality of substrates  $[(4)]$  fitted with the semiconductor chips  $[(5)]$  for a predefined processing and/or control time by means of the processing and/or control units  $[(19)]$ ;
- moving the processing and/or control units  $[(19)]$  into an open position away from the plane of the conveyor belt following expiring of the processing and/or control time;
- closing the second clamping device  $[(23)]$  which is fixed to the apparatus;
- opening the first clamping device  $[(13, 14)]$ ;
- returning the curing device (~~3, 3a, 3b, 3c, 3d~~) and/or the further device to a starting position in a direction counter to the transport direction.

11. (Currently amended) The method as claimed in claim 10, characterized in that the step of moving the processing and/or control units  $[(19)]$  into an open position can be carried out independently of a movement of the conveyor belt  $[(6)]$  in the transport direction.

12. (Currently amended) The method as claimed in claim 10 [[or 11]],  
characterized in that the transport speed corresponds to a fitting speed at which  
the substrates [[(4)]] on the conveyor belt [[(6)]] are fitted, said conveyor belt  
moving in a step-wise manner.
13. (New) The method as claimed in claim 11, characterized in that the transport  
speed corresponds to a fitting speed at which the substrates on the conveyor  
belt are fitted, said conveyor belt moving in a step-wise manner.